深圳市晶盟电子科技有限公司

Specification

规格承认书

customer(客户名称):_____

Type(产品型号):______JM-2835RGB001______

Date(编制时间):_____

Approval				
confirmation制作	checked 审核	Approved 批准		
陈权核				
Rev(版本): 4	A/0 Date	(日期):		

Customer Signatures 客户回签					
Confirmtion 确认		Date	日期		

1. Features 特性

- Top View White LED
- High luminous intensity and high efficiency
- Package size: $2.8 \times 3.5 \times 1.1$ mm
- Wide viewing angle : 120°
- Soldering methods: Reflow soldering
- RoHS compliant

2. Applications 应用

- Indoor Lighting 室内照明
- Outdoor Lighting 室外照明

3. Package Dimensions 外形尺寸







TOP 型贴片 LED

封装尺寸: 2.8×3.5×1.1mm

高亮度高效率

宽角度: 120°

符合 RoHS 标准

可回流焊接

Notes(备注):

- (1) 中间为红光,缺口为负极, 蓝光;
- (2). All dimensions are in millimeters. 所有尺寸单位均为毫米;
- (3). Without special declared, the tolerance is ± 0.1 mm.无特别注明尺寸公差为 ± 0.1 mm。

Parameter	Symbol	Rating	Unit
**	符号	数值	单位
R/G/B Forward Current 正向电流	IF	20	mA
Junction Temperature 结温	Tj	110	Ĉ
Operating Temperature 工作温度	Topr	-40 to +85	°C
Storage Temperature 存储温度	Tstg	-40 to +90	°C
Electrostatic Discharge 静电	ESD	1000	v
Soldering Temperature ² 焊接温度	Tsol	255±5	°C
Reverse Voltage 逻辑电源电压	\mathbf{V}_{in}	5~24	v

4. Absolute Maximum Ratings at Ta = 25C 极限参数(25C)

Notes: (1). 1/10 duty cycle, 0. 1ms pulse width. (2). Soldering time ≤ 5 seconds.

5. Electro-Optical Characteristics (Ta=25C) 光电参数 (25C)

Parameter	Symbol 符号	Conditions 条件		/in. 小值	Typ. 典型值	Max. 最大值	Unit 单位
Forward voltage			R	1.8	2.0	2.2	
正向电压	$V_{\rm F}$	$I_F=20 mA$	G	2.8	3.2	3.4	V
			В	2.8	3.2	3.4	1
Main wavelength 主波长	λd	IF=20mA	R	620		625	nm
			G	520		525	
			В	465		472	
Luminous Flux 光强	Φ	IF=20mA	R	500		800	
			G	1000		1300	mcd
			В	300		500	
Viewing angle 角度	20 1/2	$I_F=20 mA$			120		Deg
Reverse current 反向电流	Ir	$V_R = 5V$				10	μΑ

Notes(备注):

(1). $2 \theta 1/2$ is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2 @ 1/2 是半值脚,指光强是光学中心线光强的 1/2 处到光学中心线的角度

6. Reliability test items and conditions 性赖性测试项目及条件

● Test Items 测试项目

Item 项目	Test Conditions 试验条件	Test Hours/ Cycle 测 试时间	Sample Size 样品数量
Solder Heat 回流焊	Tsol=260 °C , 10sec (Pre-treatment 30 °C ,70% , 168h)	2 times	22 pcs
Temperature Cycle 温度循环	-40 °C 30min~25 °C,5min ~ 100 °C,30min~25 °C,5min	300 cycles	22 pcs
Thermal Shock 冷热冲击	-40°C,15min~125°C , 15min	300 cycles	22 pcs
High Temperature Storage 高温存储	Ta=100 ℃	1000 hrs	22 pcs
Low Temperature Storage 低温存储	Ta=-40 ℃	1000 hrs	22 pcs
Wet High Temperature Storage 高温高湿存储	Ta=60 ℃ , 90% RH	1000 hrs	22 pcs

Failure Criteria 失效标准

Items	Symbols	Test Conditions	Limits
项目	符号	测试条件	判定标准
Forward Voltage			
正向电压	VF	I=20mA*3	> U.S.L* 1. 1
Luminous Flux			
光强	Φ	I=20mA*3	< L.S.L*0.7

Notes: U.S.L : Upper Specification Limit; L.S.L : Lower Specification Limit. U.S.L : 规格上限值; L.S.L : 规格下限值。



8. Precautions For Use 使用注意事项

- Storage 存储
- a) Do not open moisture proof bag before the products are ready to use.
 未准备使用时,不能打开密封防潮袋。
- b) Before opening the package, the LEDs should be kept at 30℃ or less and 60% RH or less. 开封前,产品需存放于温度不高于 30℃, 湿度不超过 60%的环境中。
- c) After opening the package, the LEDs should be stored at 30 °C or less and 10% RH or less, and be soldered within 2 4 hours. It is recommended that the product be operated at the workshop condition of 3 0 °C or less and 60% RH or less.

开封后,产品需存放于温度不高于 30℃, 湿度不超过 10%的环境中,且应该在 12 小时内使用完,建 议工作环境温度不高于 30℃, 湿度不超过 60%

d) If the moisture absorbent material has fade away or the LEDs have exceeded the storage time, baking treatment should be performed on the following condition: 80℃ for 24 hours.

对于尚未焊接的 LED,如果吸湿剂或包装失效,或者产品没有符合以上有效存储条件,烘焙可以起到 一定的性能恢复效果。烘焙条件: 70℃, 持续 24 小时。同时联系我司安排退换货处理。

- Static Electricity 防静电
- The LEDs are sensitive to the static electricity and surge voltage. Damaged LEDs may show some unusual characteristics such as increase in leak current, lowered turn-on voltage, or abnormal lighting of LEDs at low current.

LED 对静电和浪涌电压很敏感。因此损坏的 LED 会导致某些产品特性发生变化,例如启动电压降低,漏电流增大,如果情况严重甚至损毁产品。

2) All devices, equipment and machinery must be properly grounded. It is recommended that wrist band or anti-electrostatic gloves, anti-electrostatic containers be used when dealing with the LEDs.

所有相关设备和机器都应该正确接地。在使用 LED 时,建议使用防静电的手环、垫子、手套,防静 电电容器等工具。

Handling Indications 处理防备措施



- Handle the component along the side surface by using forceps or appropriate tools. 通过使用适当的工具从材料侧面夹取。
- Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry. 不可直接用手或尖锐金属压胶体表面,它可能会损坏内部电路。
- Do not stack together assembled PCBs containing the internal circuitry. 不可将模组材料堆积在一起,它可能会损坏内部电路。

• Soldering Conditions 焊接条件

Reflow Soldering Conditions (Pb Free) 无铅回流焊条件 Above255℃ 30sec Max 3 ℃ sec Max 3 ℃ sec Max Above 217 60~150 sec 6℃ Max 6 ℃ sec. Max

- 1) Reflow soldering should not be done more than two times. 回流焊不可超过两次。
- When soldering, do not put stress on the LEDs during heating. 当回焊时,不可用力压胶体表面。

For Manual Soldering 手工焊接条件

1) When hand soldering, the temperature of the iron must less than 300 $^\circ\!\!\mathbb{C}$ for 3 seconds.

当手工焊接时, 烙铁的温度必须小于 300℃, 时间不可超过 3 秒。

- The hand solder should be done only one times 手工焊接只可焊接一次。
- Repairing 维修

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

LED 回流焊后不应该修补,当修复是不可避免的时,必须使用双头烙铁 (如下图),但必须事先确认此种方 式会或不会损坏 LED 本身的特性。

